

# Xe Architecture

Scaling from 10W to 500W

Alchemist GPU



# Challenges

- Scaling of Xe Architecture across segments
  - Maintain a single IP
    - ~30x Range in TFs<sup>1</sup> & ~50x Range in power<sup>1</sup>
      - 10W to 500W
      - 2TFs to 60TFs
    - Varied capabilities / optimization points
- Scalable Slice Architecture
  - Scalable Xe-Cores
  - Efficiency in balancing resources

<sup>1</sup> Example, Varies on final product, process technology choice

# Xe HPG

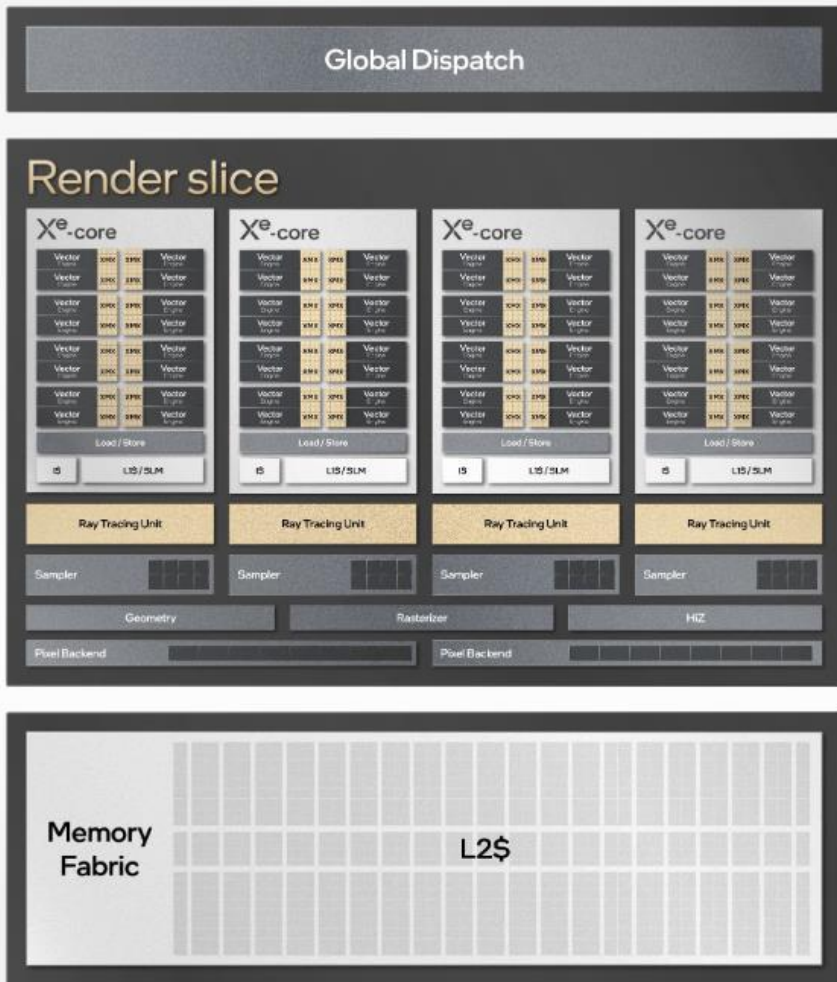
## Scaling the Graphics Engine

**Xe-Cores with XMX**

**Ray Tracing Units**  
Ray Traversal  
Bounding Box Intersection  
Triangle Intersection

**Fixed Function**  
Optimized for DX12 Ultimate

**Unified L2\$**  
High BW, Low Latency



# Render Slice

4 X<sup>e</sup>-cores with XM<sup>X</sup>

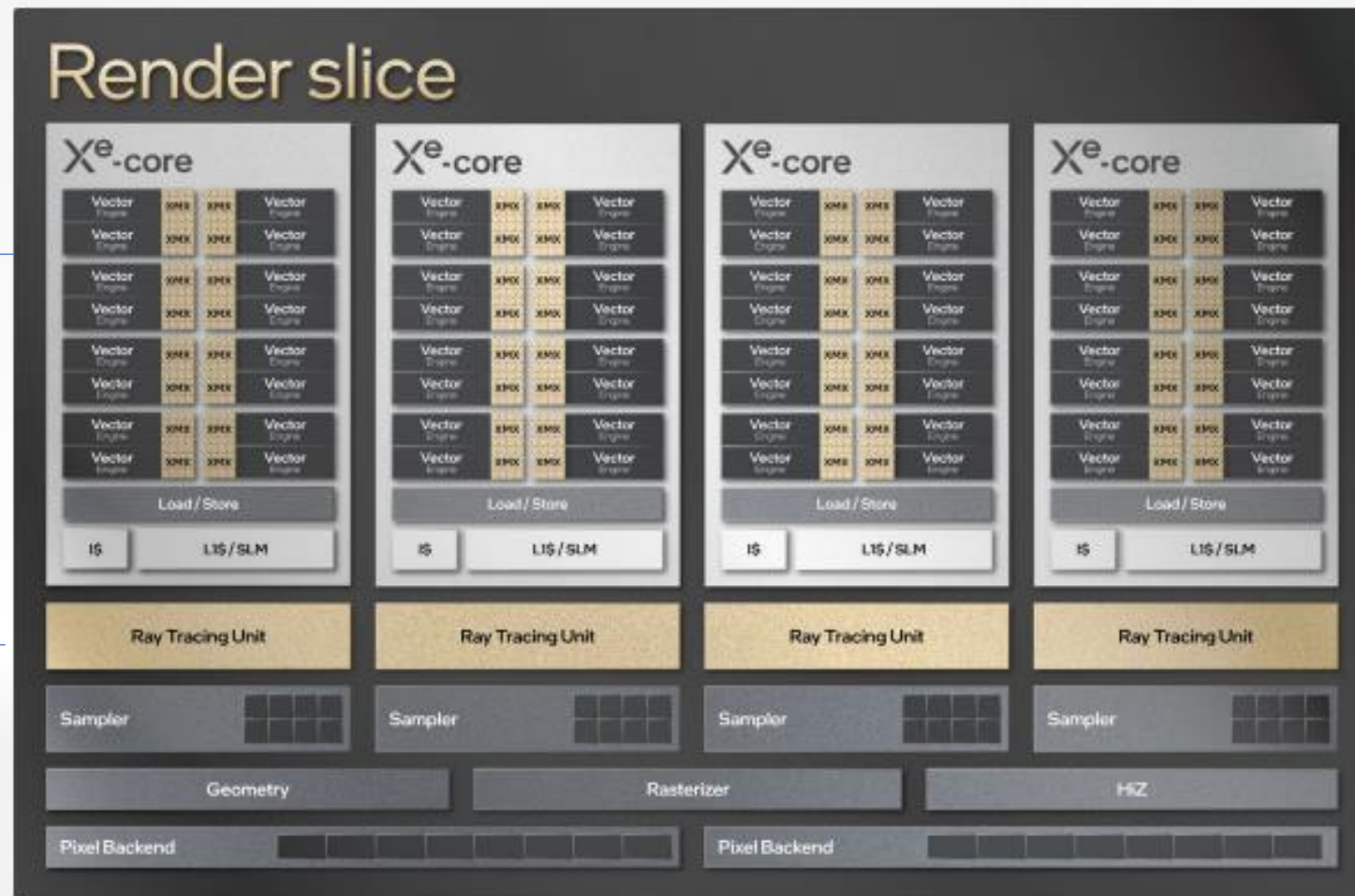
4 Ray Tracing Units

Ray Traversal

Bounding Box Intersection

Triangle Intersection

Fixed Function  
optimized for DX12  
Ultimate Gaming





# Xe-core

Compute Building Block of Xe HPG-based GPUs

**16**  
Vector Engines

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**256 bit**  
per engine

**16**  
Matrix Engines

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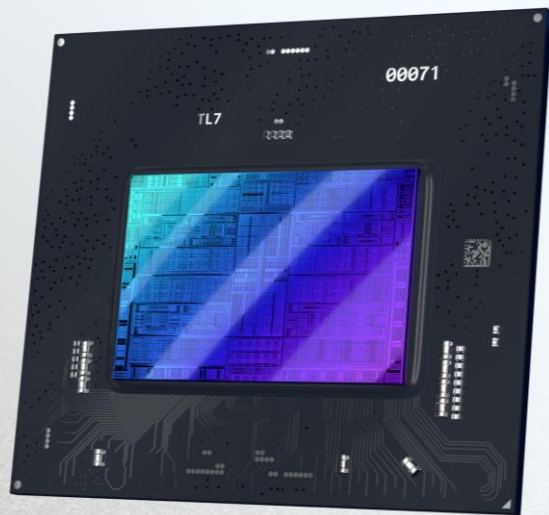
**1024 bit**  
per engine

# Multi-Year d-GPU Road

Performance ↑

## Alchemist

X<sup>e</sup> HPG



## Battlemage

X<sup>e2</sup> HPG



## Celestial

X<sup>e3</sup> Architecture



## Druid

X<sup>e</sup> Next Architecture



intel<sup>®</sup>  
**ARC**<sup>™</sup>



# THE FUTURE – EFFICIENT SOLUTIONS REQUIRE EXPLORATION

## One IP

### LP (iGFX)

- Low Power (6 – 30W)
- Content Creation, ML

### HPG (dGFX)

- High Power (100 – 500W)
- Path trace, Neural Rendering

### HPC (DataCenter)

- High Density OPs
- HPC, AI, ML

Continue the One IP

Balance of machine for optimum raw performance, performance/W, performance/mm<sup>2</sup>.

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